FEATURES:

- · 1 to 10 differential clock distribution
- Optimized for clock distribution in DDR2 (Double Data Rate) SDRAM applications
- Operating frequency: 125MHz to 410MHz
- Stabilization time: <6us
- Very low skew: ≤40ps
- Very low jitter: ≤40ps
- 1.8V AVDD and 1.8V VDDQ
- CMOS control signal input
- Test mode enables buffers while disabling PLL
- Low current power-down mode
- Tolerant of Spread Spectrum input clock
- · Available in 52-Ball VFBGA and 40-pin VFQFPN packages

APPLICATIONS:

- Meets or exceeds JEDEC standard CUA877 for registered DDR2 clock driver
- Along with SSTUA32864/66, DDR2 register, provides complete solution for DDR2 DIMMs

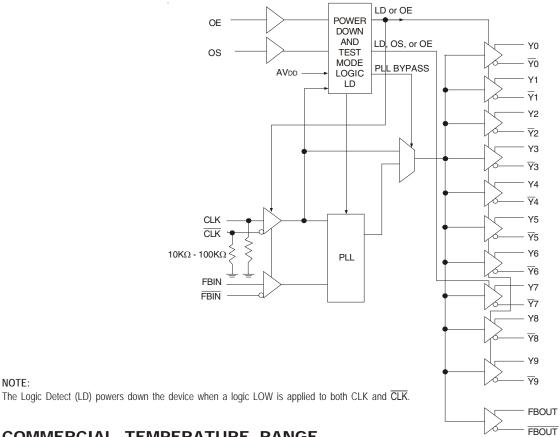
DESCRIPTION:

The CSPUA877A is a PLL based clock driver that acts as a zero delay buffer to distribute one differential clock input pair(CLK, CLK) to 10 differential output pairs (Y [0:9], Y [0:9]) and one differential pair of feedback clock output (FBOUT, FBOUT). External feedback pins (FBIN, FBIN) for synchronization of the outputs to the input reference is provided. OE, OS, and AVDD control the power-down and test mode logic. When AVDD is grounded, the PLL is turned off and bypassed for test mode purposes. When the differential clock inputs (CLK, CLK) are both at logic low, this device will enter a low power-down mode. In this mode, the receivers are disabled, the PLL is turned off, and the output clock drivers are disabled, resulting in a clock driver current consumption of less than 500 µA.

The CSPUA877A requires no external components and has been optimised for very low phase error, skew, and jitter, while maintaining frequency and duty cycle over the operating voltage and temperature range. The CSPUA877, designed for use in both module assemblies and system motherboard based solutions, provides an optimum high-performance clock source.

The CSPUA877A is available in Commercial Temperature Range (0°C to +70°C). See Ordering Information for details.

FUNCTIONAL BLOCK DIAGRAM



COMMERCIAL TEMPERATURE RANGE

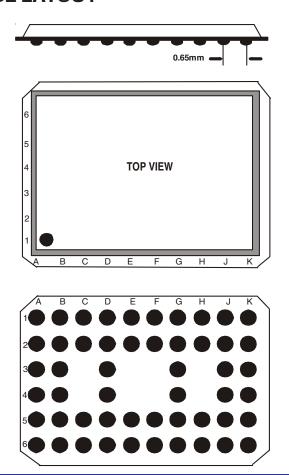
NOVEMBER 2008

PIN CONFIGURATION

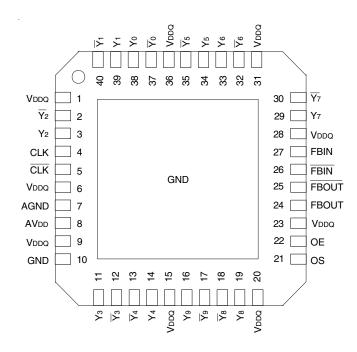
_					I	I	I			
6	Y6	<u>Y6</u>	<u>Y7</u>	Y 7	FBIN	FBIN	FBOUT	FBOUT	Y8	<u>Y8</u>
5	Y 5	GND	GND	os	VDDQ	OE	VDDQ	GND	GND	<u>Y</u> 9
4	<u>Y</u> 5	GND	NB	VDDQ	NB	NB	VDDQ	NB	GND	Y 9
3	Y ₀	GND	NB	VDDQ	NB	NB	VDDQ	NB	GND	Y 4
2	Y0	GND	GND	VDDQ	VDDQ	VDDQ	VDDQ	GND	GND	<u>Y</u> 4
1	Y1	<u>Y1</u>	Y2	Y2	CLK	CLK	AGND	AVDD	Y 3	<u>Y</u> 3
	A	В	С	D	Е	F	G	Н	J	K

VFBGA TOP VIEW

52 BALL VFBGA PACKAGE LAYOUT



PIN CONFIGURATION, CONT.



VFQFPN TOP VIEW

ABSOLUTE MAXIMUM RATINGS(1,2)

Symbol	Rating	Max	Unit
Vddq, AVdd	Supply Voltage Range	-0.5 to +2.5	V
VI ⁽³⁾	Input Voltage Range	-0.5 to V _{DDQ} + 0.5	V
Vo ⁽³⁾	Voltage range applied to any	-0.5 to VDDQ + 0.5	V
	output in the high or low state		
lıĸ	Input clamp current	±50	mA
(VI <0)			
Іок	Output Clamp Current	±50	mA
(Vo <0 or			
Vo > Vddq)			
lo	Continuous Output Current	±50	mA
(Vo =0 to VDDQ)			
VDDQ or GND	Continuous Current	±100	mA
TSTG	Storage Temperature Range	- 65 to +150	°C

NOTES:

- Stresses greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause
 permanent damage to the device. This is a stress rating only and functional operation of
 the device at these or any other conditions above those indicated in the operational
 sections of this specification is not implied. Exposure to absolute maximum rating
 conditions for extended periods may affect reliability.
- The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils.
- The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed. This value is limited to 2.5V max.

CAPACITANCE(1)

Parameter	Description	Min.	Тур.	Max.	Unit
CIN	Input Capacitance	2	_	3	pF
	VI = VDDQ or GND				
CιΔ	Delta Input Capacitance			0.25	pF
	CLK, CLK, FBIN, FBIN				
CL	Load Capacitance	_	10	_	pF

NOTE:

1. Unused inputs must be held high or low to prevent them from floating.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min.	Тур.	Max.	Unit
AV _{DD} ⁽¹⁾	Supply Voltage		VDDQ		V
VDDQ	I/O Supply Voltage	1.7	1.8	1.9	V
TA	Operating Free-Air Temperature	0	_	+70	°C

NOTE:

1. The PLL is turned off and bypassed for test purposes when AVpb is grounded. During this test mode, Vpbc remains within the recommended operating conditions and no timing parameters are guaranteed.

PIN DESCRIPTION (VFBGA)

Pin Name	Pin Number	Description
AGND	G1	Ground for 1.8V analog supply
AVdd	H1	1.8V analog supply
CLK, CLK	E1, F1	Differential clock input with a 10K Ω to 100K Ω pulldown resistor
FBIN, FBIN	E6, F6	Feedback differential clock input
FBOUT, FBOUT	G6, H6	Feedback differential clock output
GND	B2 - B5, C2, C5, H2, H5, J2 - J5	Ground
VDDQ	D2 - D4, E2, E5, F2, G2 - G5	1.8V supply
OE	F5	Output Enable
OS	D5	Output Select (tied to GND or VDDO)
<u>Y[0:9]</u>	A3, A4, B1, B6, C1, C6, K1, K2, K5, K6	Buffered output of input clock, CLK
Y[0:9]	A1, A2, A5, A6, D1, D6, J1, J6, K3, K4	Buffered output of input clock, CLK
NB		No Ball

PIN DESCRIPTION (VFQFPN)

Pin Name	Pin Number	Description
AGND	7	Ground for 1.8V analog supply
AVdd	8	1.8V analog supply
CLK, CLK	4, 5	Differential clock input with a 10K Ω to 100K Ω pulldown resistor
FBIN, FBIN	26,27	Feedback differential clock input
FBOUT, FBOUT	24,25	Feedback differential clock output
GND	10	Ground
VDDQ	1, 6, 9, 15, 20, 23, 28, 31, 36	1.8V supply
OE	22	Output Enable
OS	21	Output Select (tied to GND or Voda)
Y[0:9]	3, 11, 14, 16, 19, 29, 33, 34, 38, 39	Buffered output of input clock, CLK
Y[0:9]	2, 12, 13, 17, 18, 30, 32, 35, 37, 40	Buffered output of input clock, CLK
NB		No Ball

FUNCTION TABLE(1,2)

		INPUT	S						
AVDD	OE	OS	CLK	CLK	Υ	Ÿ	FBOUT	FBOUT	PLL
GND	Н	Х	L	Н	L	Н	L	Н	OFF
GND	Н	Х	Н	L	Н	L	Н	L	OFF
GND	L	Н	L	Н	L(z)	L(z)	L	Н	OFF
					L(z)	L(z)			
GND	L	L	Н	L	Y 7	Y 7	Н	L	OFF
					Active	Active			
1.8V (nom)	L	Н	L	Н	L(z)	L(z)	L	Н	ON
					L(z)	L(z)			
1.8V (nom)	L	L	Н	L	Y 7	Y 7	Н	L	ON
					Active	Active			
1.8V (nom)	Н	Х	L	Н	L	Н	L	Н	ON
1.8V (nom)	Н	Х	Н	L	Н	L	Н	L	ON
1.8V (nom)	Χ	Х	L ⁽³⁾	L ⁽³⁾	L(z)	L(z)	L(z)	L(z)	OFF
Х	Х	Х	Н	Н	Reserved				

NOTES:

- H = HIGH Voltage Level
 L = LOW Voltage Level

 - X = Don't Care
- 2. L(z) means the outputs are disabled to a LOW state, meeting the lool limit in DC Electrical Characteristics table.
- 3. The device will enter a low power-down mode when CLK and $\overline{\text{CLK}}$ are both at logic LOW.

DC ELECTRICAL CHARACTERISTICS OVER OPERATING RANGE

Following Conditions Apply Unless Otherwise Specified:

Commercial: $TA = 0^{\circ}C$ to $+70^{\circ}C$

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Vik	Input Clamp Voltage (All Inputs)	VDDQ = 1.7V, II = -18mA	_	_	-1.2	V
VIL ⁽²⁾	Input LOW Voltage (OE, OS, CLK, CLK)		_	_	0.35VDDQ	V
VIH ⁽²⁾	Input HIGH Voltage (OE, OS, CLK, CLK)		0.65Vddq	_	_	
VIN ⁽¹⁾	Input Signal Voltage		-0.3	_	VDDQ + 0.3	V
VID(DC) ⁽²⁾	DC Input Differential Voltage		0.3		VDDQ + 0.4	V
VoD ⁽³⁾	Output Differential Voltage	AVDD/VDDQ = 1.7V	0.6	_	_	V
Voн	Output HIGH Voltage	IOH = -100μA, VDDQ = 1.7V to 1.9V	VDDQ - 0.2		_	V
		IOH = -9mA, VDDQ = 1.7V	1.1		_	
Vol	Output LOW Voltage	IOL = 100μA, VDDQ = 1.7V to 1.9V			0.1	V
		IOL = 9mA, VDDQ = 1.7V			0.6	
IODL	Output Disabled LOW Current	OE = L, VODL = 100mV, AVDD/VDDQ = 1.7V	100	_	_	μА
lin	Input Current CLK, CLK	AVDD/VDDQ = Max., VI = 0V to VDDQ			±250	μΑ
	OE, OS, FBIN, FBIN				±10	
Iddld	Static Supply Current (IDDQ and IADD)	AVDD/VDDQ = Max., CLK and $\overline{\text{CLK}}$ = GND			500	μΑ
IDD	Dynamic Power Supply Current	AVDD/VDDQ = Max., CLK = 410MHz			300	mA
	(IDDQ and IADD) ^(4,5)					

NOTES:

- 1. VIN specifies the allowable DC excursion of each different output.
- 2. VID is the magnitude of the difference between the input level on CLK and the input level on CLK and The CLK an
- 3. Vop is the magnitude of the difference between the true output level and the complementary level.
- 4. All Outputs are left open (unconnected to PCB).
- 5. Total IDD = IDDQ + IADD = FCK * CPD * VDDQ, for CPd = (IDDQ + IADD) / (FCK * VDDQ) where FCK is the input frequency, VDDQ is the power supply, and CPD is the Power Dissipation Capacitance.

TIMING REQUIREMENTS

Symbol	Parameter	Min.	Max.	Unit
fclk	Operating Clock Frequency ^(1,2,5)	125	410	MHz
	Application Clock Frequency ^(1,3,5)	160	410	MHz
toc	Input Clock Duty Cycle	40	60	%
t_	Stabilization Time ⁽⁴⁾	_	6	μs

NOTES:

- 1. The PLL will track a spread spectrum clock input.
- 2. Operating clock frequency is the range over which the PLL will lock, but may not meet all timing specifications. To be used only for low speed system debug.
- 3. Application clock frequency is the range over which timing specifications apply.
- 4. Stabilization time is the time required for the integrated PLL circuit to obtain phase lock of its feedback signal to its reference signal after power up. During normal operation, the stabilization time is also the time required for the PLL circuit to obtain phase lock of its feedback signal to its reference signal when CLK and CLK go to a logic LOW state, enters the power-down mode, and later return to active operation. CLK and CLK may be left floating after they have been driven LOW for one complete clock cycle.
- 5. Will lock to input frequency as low as 30MHz at room temperature and nominal or higher supply voltage (1.8V 1.9V).

AC ELECTRICAL CHARACTERISTICS(1)

Symbol	Description	fcк (MHz)	Min.	Typ. ⁽²⁾	Max.	Unit
ten	OE to any Y/Y	160 to 410	_	_	8	ns
tdis	OE to any Y/Y	160 to 410	_	_	8	ns
SLR(I)	Output Enable (OE)	160 to 410	0.5	_	_	V/ns
	Input Clock Slew Rate, measured single-ended	160 to 410	1	2.5	4	
SLR(O) ⁽⁴⁾	Output Clock Slew Rate, measured single-ended	160 to 410	1.5	2.5	3	V/ns
Vox ⁽⁶⁾	Output Differential-Pair Cross-Voltage	160 to 410	(VDDQ/2)-0.1	_	(VDDQ/2)+0.1	V
tJIT(CC+)	Cycle-to-Cycle Period Jitter	160 to 410	0	_	40	ps
tjit(cc-)	Cycle-to-Cycle Period Jitter	160 to 410	0	_	-40	ps
t(∅) ⁽⁵⁾	Static Phase Offset	160 to 410	-50	_	50	ps
t(∅)DYN ⁽⁷⁾	Dynamic Phase Offset	160 to 270	-50	_	50	ps
		271 to 410	t(∅)DYN(MIN)	_	t(∅)DYN(MAX)	
tsk(0) ⁽⁷⁾	Output Clock Skew	160 to 270	_	_	40	ps
		271 to 410	_	_	tsk(o)max	
tjit(per) ^(3,7)	Period Jitter	160 to 270	-40	_	40	ps
		271 to 410	tjit(per)min	_	tjit(per)max	
tJIT(HPER) ⁽³⁾	Half-Period Jitter	160 to 270	-75	_	75	ps
		271 to 410	-50	_	50	
Σ t(SU) $^{(7)}$	tjit(per) + t(Ø)dyn + tsk(0)	271 to 410	_	_	80	ps
$\Sigma t(H)^{(7)}$	t(Ø)DYN + tSK(O)	271 to 410	_	_	60	ps
The PLL on th	ne CSPUA877A will meet all the above test parameters	s while supporting SSC synthesizers with the fo	ollowing parame	ters:		
	SSC Modulation Frequency		30		33	KHz
	SSC Clock Input Frequency Deviation		0	_	0.5	%
CSPUA877A	PLL designs should target the value below to minimiz	e SSC-induced skew:				
	PLL Loop Bandwidth (-3dB from unity gain)		2	_	_	MHz

NOTES:

- 1. There are two different terminations that are used with the above AC tests. The output load shown in figure 1 is used to measure the input and output differential pair cross-voltage only. The output load shown in figure 2 is used to measure all other tests, including input and output slew rates. For consistency, use 50Ω equal length cables with SMA connectors on the test board.
- 2. Refers to transition of non-inverting output.
- 3. Period jitter and half-period jitter specifications are seperate specifications that must be met independently of each other.
- 4. To eliminate the impact of input slew rates on static phase offset, the input slew rates of reference clock input (CLK, CLK) and feedback clock input (FBIN, FBIN) are recommended to be nearly equal. The 2.5V/ns slew rates are shown as a recommended target. Compliance with these nominal values is not mandatory if it can be adequately demonstrated that alternative characteristics meet the requirements of the registered DDR2 DIMM application.
- 5. Static phase offset does not include jitter.
- 6. Vox is specified at the DDR DRAM clock input or test load.
- 7. In the frequency range of 271 410MHz, the min and max values for Litt(PER) and t(Ø)DYN, and the max value for tsk(o), must not exceed the corresponding min and max values of the 160 270MHz range. Also, the sum of the specified values for | tJIT(PER) |, | t(Ø)DYN |, and tSK(O) must meet the requirement for Σt(SU), and the sum of the specified values for | t(Ø)DYN | and tSK(O) must meet the requirement for Σt(H).

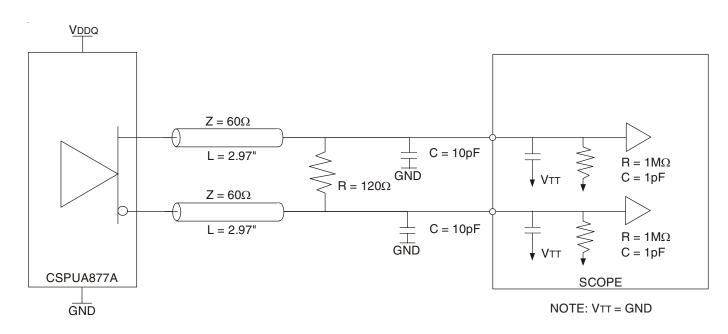


Figure 1: Output Load Test Circuit 1

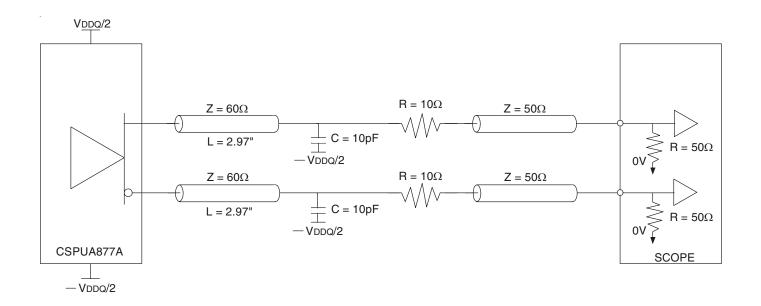
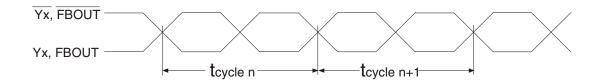


Figure 2: Output Load Test Circuit 2

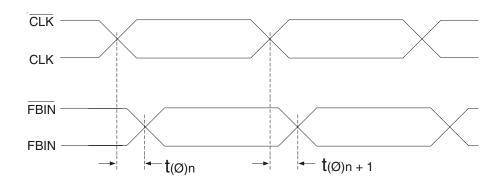
(N is a large number of samples)

TEST CIRCUIT AND SWITCHING WAVEFORMS



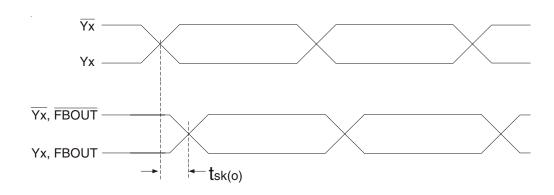
 $t_{jit(cc)} = t_{cycle n} - t_{cycle n+1}$

Cycle-to-Cycle jitter

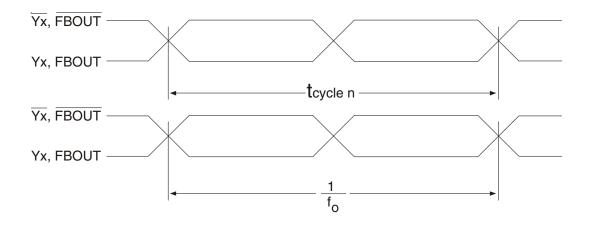


$$t_{(\emptyset)} = \frac{\sum_{1}^{n = N} t_{(\emptyset)n}}{N}$$

Static Phase Offset



Output Skew

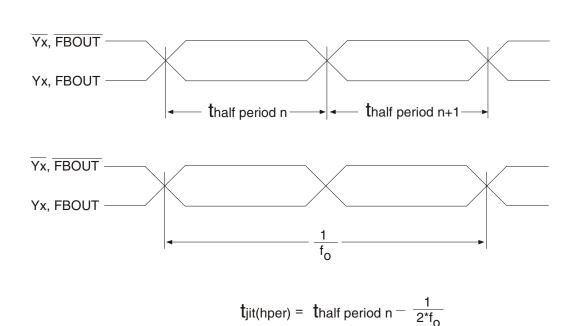


$$t_{jit(per)} = t_{cycle} n - \frac{1}{f_0}$$

NOTE:

fo = Average input frequency measured at CLK / $\overline{\text{CLK}}$

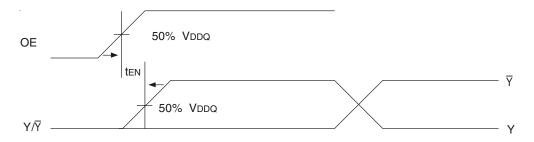
Period jitter

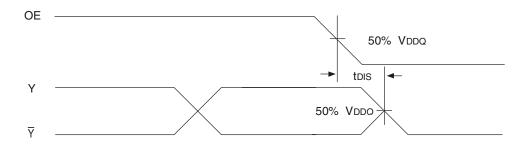


NOTE:

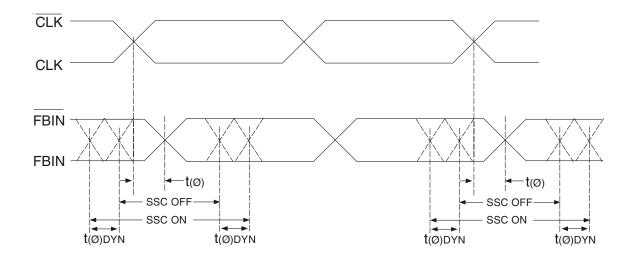
fo = Average input frequency measured at CLK / $\overline{\text{CLK}}$

Half-Period jitter

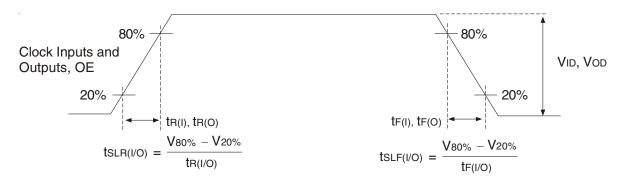




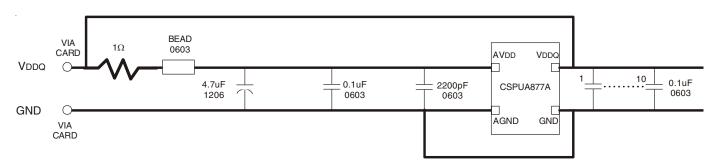
Time Delay Between Output Enable (OE) and Clock Output (Y, \overline{Y})



Dynamic Phase Offset



Input and Output Slew Rates



NOTES:

Place all decoupling capacitors as close to the CSPUA877A pins as possible.

Use wide traces for AVDD and AGND.

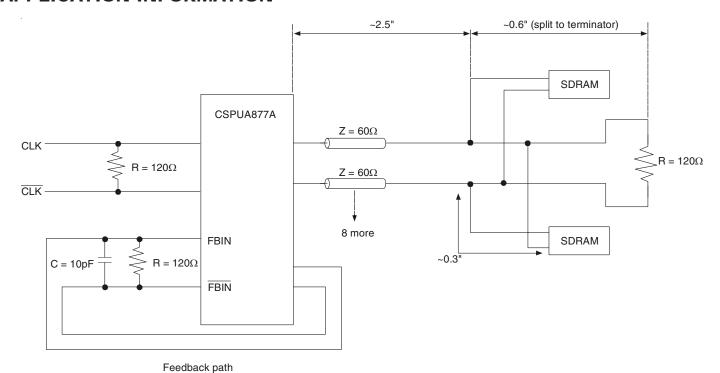
Recommended bead: Fair-rite P/N 2506036017Y0 or equivalent (0.8 Ω DC max., 600 Ω at 100MHz).

Recommended Filtering for the Analog and Digital Power Supplies (AVDD and VDDQ)

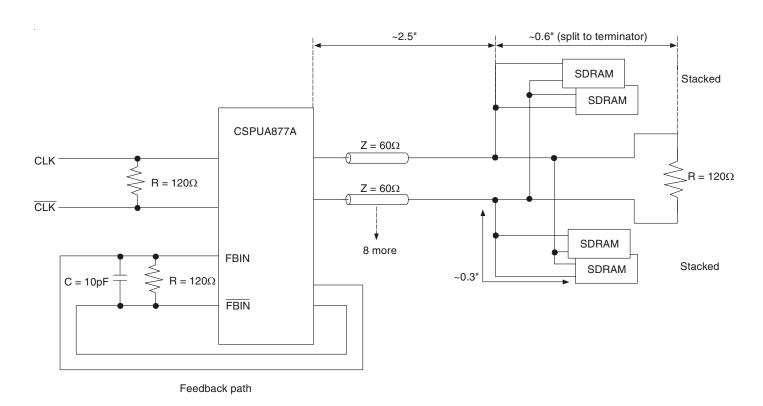
APPLICATION INFORMATION

		Clock Loading on the PLL outputs (pF)		
Clock Structure	# of SDRAM Loads per Clock	Min.	Max.	
#1	2	3	5	
#2	4	6	10	

APPLICATION INFORMATION

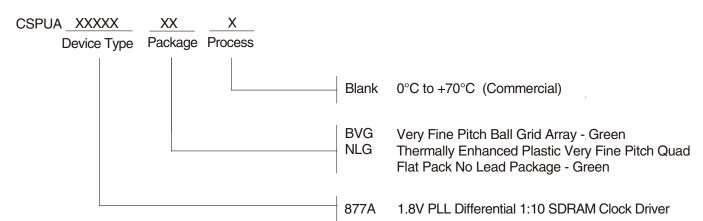


Clock Structure 1



Clock Structure 2

ORDERING INFORMATION



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